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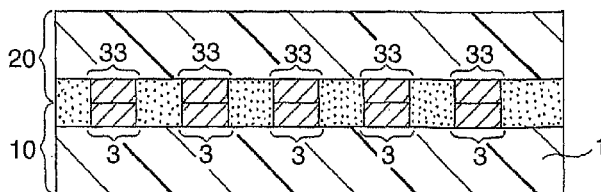
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(54) Title: METHOD FOR CONNECTING PRINTED CIRCUIT BOARDS



(57) Abstract: To provide a method for connecting printed circuit boards with high connection reliability, while avoiding the problem of shorting even with a fine pitch. A method for connecting printed circuit boards (PCB) containing metal wiring, or connecting a printed circuit board (PCB) containing metal wiring with a metal lead wire or a metal contact, which method includes a step of thermocompression bonding of an adhesive film with connectors, the adhesive film being composed of an adhesive composition comprising a thermoplastic resin and organic particles, wherein the viscosity decreases as the applied thermocompression force increases at a temperature of 100-250°C.



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